

**EAST Search History****EAST Search History (Prior Art)**

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	7	US-5686353-\$.DI D. OR US-20030148593-\$.DI D. OR US-20040169020-\$.DI D. OR JP-2000138255-\$.DI D. OR JP-2000138255051600-\$.DI D. OR JP-63101085-\$.DI D. OR JP-63101085050688-\$.DI D. OR JP-2001351892-\$.DI D. OR JP-2001351892122101-\$.DI D. OR JP-57195593-\$.DI D. OR JP-57195593120182-\$.DI D. OR JP-8181144-\$.DI D. OR JP-8181144071296-\$.DI D. OR JP-2791429-\$.DI D. OR JP-2791429082798-\$.DI D. OR JP-1092702-\$.DI D.	US-PGPUB; USPAT; USOCR; EPO; JPO	OR	ON	2008/11/24 10:58
S2	146	suga-tadatomo.in. or okada-masuaki.in.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/24 11:14
S3	5	S2 and bond\$3 same (gold or Au or copper or Cu) same solid\$3 same (chip or wafer or substrate) and ((energy near5 treat\$4) or beam or atom\$3 or ion or plasma)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/24 11:26
S4	112	KIMURA-TAKEHI RO.in. or ISOZAKI -SEI YA.in. or HASHIMOTO-KATSUMASA.in.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/24 11:29
S5	4	S4 and bump\$3 same (gold or Au) same bond\$3 and (chip or wafer or substrate) and (beam or plasma)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/24 11:30
S6	10	("5604379"   "5672912"   "5874784"   "5892271"   "5953592"   "6140707"   "6232650").PN. OR ("6400034").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/11/24 11:34
S7	2158	228/116,180.21,180.22.ccls.	US-PGPUB; USPAT; USOCR	OR	ON	2008/11/24 11:45
S9	1803	438/455.ccls.	US-PGPUB; USPAT; USOCR	OR	ON	2008/11/24 11:47

S10	6	(S7 or S9) and (solid near5 (state or phase) same bond\$3 same (room or ambient or low) near5 temperature and (gold or Au) same (chip or wafer or substrate) and (beam or plasma))	US-PGPUB; USPAT; USOCR	OR	ON	2008/11/24 11:49
S11	0	EP-711097-4.did.	US-PGPUB; USPAT; USOCR	OR	ON	2008/11/24 14:25
S12	2	EP-711097-\$.did.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/24 14:25
S13	8	("5407864"   "5912507").PN. OR ("6288445").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/11/24 16:31
S14	89204	toray.as.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/24 16:49
S15	0	S14 and tadatomo-suga.in. and bond\$3 same room same temperature	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/24 16:50
S16	397	S14 and bond\$3 same room same temperature	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/24 16:50
S17	395	S14 and bond\$3 same room near5 temperature	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/24 16:50
S18	4	S14 and bond\$3 same room near5 temperature and energy same wave same clean\$3	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/24 16:51
S22	4	"2004047127"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/24 17:00

S23	2	"20040047127"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/24 17:00
S24	3	"20060016555"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/24 17:11
S25	89207	toray.as.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/25 14:00
S26	395	S25 and bond\$3 same room near5 temperature	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/25 14:00
S27	0	S26 and (copper or cu) near10 (pad or pads or electrode or electrodes or land or lands) same diffus\$4 same (au or gold)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/25 14:00
S28	2160	228/116,180.21,180.22.ccls.	US-PGPUB; USPAT; USOCR	OR	ON	2008/11/25 14:00
S29	1806	438/455.ccls.	US-PGPUB; USPAT; USOCR	OR	ON	2008/11/25 14:00
S30	29	(S28 or S29) and (copper or cu) near10 (pad or pads or electrode or electrodes or land or lands) same diffus\$4 same (au or gold)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/25 14:00
S31	2	("5833758").PN.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/11/25 15:46
S32	0	RF near10 plasma same clean\$3 same rough\$4 near10 Ry	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/25 15:55

S33	1	plasma same clean\$3 same rough\$4 near10 Ry	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/25 15:55
S34	1	RF same plasma same clean\$3 and rough\$4 near10 Ry	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/25 15:55
S35	7	plasma same clean\$3 and rough\$4 near10 Ry	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/25 15:57
S36	540	plasma same clean\$3 and rough\$4 near10 Ra	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/25 16:06
S37	40	RF same plasma same clean\$3 and rough\$4 near10 Ra	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/25 16:06
S38	23	S37 and @ad<"20040201"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/25 16:06
S39	76	semiconductor same bond\$3 and plasma same clean\$3 and rough\$4 near10 Ra	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/25 16:16
S40	9099711	"10" and @ad<"20040201"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/25 16:17
S41	39	S39 and @ad<"20040122"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/25 16:17

S42	2	("5686353").PN.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/11/25 17:25
S43	90875	toray.as.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/05/06 10:36
S44	3	S43 and (gold or Au) same bond \$3 same ((room near5 temperature) or ambient) and (ion or atom\$3 or plasma)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/05/06 10:36
S45	775	yamauchi-akira.in.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/05/06 10:42
S46	2	S45 and (gold or Au) same bond \$3 same ((room near5 temperature) or ambient) and (ion or atom\$3 or plasma)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/05/06 10:42
S47	0	jp-2001351892-4.did.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/05/06 10:58
S48	2	jp-2001351892-\$ did.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/05/06 10:58
S49	2	("20030164396").PN.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/05/06 11:18
S50	997	yamauchi-akira.in. azuma-kazuji. in. suga-tadatomo.in.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/11/24 11:40

S51	31	S50 and bond\$3 same (gold or Au or copper or Cu) and ((energy near5 treat\$4) or beam or atom\$3 or ion or plasma)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/11/24 11:43
S52	997	yamauchi-akira.in. azuma-kazuji. in. suga-tadatomo.in.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/11/24 14:01
S53	9	S52 and bond\$3 same room same temperature same (gold or Au or copper or Cu)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/11/24 14:01
S54	8	US-5767577-\$.DID. OR US-5384018-\$.DID. OR US-0419238-\$.DID. OR US-5802699-\$.DID. OR US-5919561-\$.DID. OR US-4992847-\$.DID. OR US-5714252-\$.DID.	US-PGPUB; USPAT; USOCR; EPO; JPO	OR	ON	2009/11/24 14:44
S55	81	bond\$3 near10 thin near5 oxide and room near5 temperature same (gold or Au or copper or Cu)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/11/24 15:18
S56	16	bond\$3 near10 thin near5 oxide and room near5 temperature same (gold or Au)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/11/24 15:22
S57	845	"228".clas. and (bond\$3 or join\$3 or solder\$3) same (gold or Au or copper or Cu) and ((energy near5 treat\$4) or beam or atom\$3 or ion or plasma) same (oxide\$1 or organic)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/12/11 16:57
S58	391	"228".clas. and (bond\$3 or join\$3 or solder\$3) same (gold or Au or copper or Cu) same ((energy near5 treat\$4) or beam or atom\$3 or ion or plasma) same (oxide\$1 or organic)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/12/11 16:58
S59	244	"228".clas. and (bond\$3 or join\$3 or solder\$3) same (gold or Au or copper or Cu) same ((thin\$4 or adher\$4 or scal\$3 or foil\$1) near5 (oxide\$1 or organic))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/12/11 17:02

S61	1362	((bond\$3 or join\$3 or solder\$3) same (gold or Au or copper or Cu) same ((thin\$4 or adher\$4 or scal\$3 or foil\$1) near5 (oxide\$1 or organic)) and @ad<"20040122"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/12/11 17:05
S62	434	((bond\$3 or join\$3 or solder\$3) same (gold or Au) same ((thin\$4 or adher\$4 or scal\$3 or foil\$1) near5 (oxide\$1 or organic)) and @ad<"20040122"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/12/11 17:05
S63	281	S62 and ((energy near5 treat\$4) or beam or atom\$3 or ion or plasma)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/12/11 17:07
S64	18	("2791429"   "20010001428"   "4992847"   "5384018"   "5714252"   "5767577"   "5802699"   "5919561"   "6218736").PN.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/12/21 13:01
S65	9	("4709844"   "4921157"   "5182628"   "5377902").PN. OR ("5767577").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2009/12/21 15:13
S66	2169	228/116,219,180.21.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/03/29 10:31
S67	75	S66 and (bond\$3 or join\$3 or solder\$3) same (plasma or atom or ion) and (gold or Au) and (thin\$4 or adher\$4 or readher\$4)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/03/29 10:48

## EAST Search History (Interference)

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S69	2296	228/116,219,180.21,180.22.ccls.	USPAT; UPAD	OR	ON	2010/03/29 10:53
S70	0	S69 and bond\$3 same (plasma or atom or ion) and crush\$3 near5 (surface or interface) same adher\$4	USPAT; UPAD	OR	ON	2010/03/29 10:57
S71	1293	438/455.ccls.	USPAT; UPAD	OR	ON	2010/03/29 10:58
S72	0	S71 and (join\$3 or solder\$3 or bond\$3) same (plasma or atom or ion) and crush\$3 near5 (surface or interface) same adher\$4	USPAT; UPAD	OR	ON	2010/03/29 10:58

S73	0	((join\$3 or solder\$3 or bond\$3) same (plasma or atom or ion) same gold same adher\$4).clm.	USPAT; UPAD	OR	ON	2010/03/29 11:05
S74	28	((join\$3 or bond\$3) and gold and (surface or interface) and (readher\$4 or adher\$4) and solid).clm.	USPAT; UPAD	OR	ON	2010/03/29 11:08
S75	32	((join\$3 or bond\$3) and gold and (irregularities or protru\$5 or project\$4) same (surface or interface) and (readher \$4 or adher\$4)).clm.	USPAT; UPAD	OR	ON	2010/03/29 11:10

3/ 29/ 2010 2:01:08 PM

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